

IN THE CLAIMS

Please amend the claims as follows:

Claim 1 (Original): In a probe device, an improved contact probe comprising:

a film;

a plurality of wiring patterns formed on the film, each wiring pattern having a front end portion projecting from the film so as to form contact pins; and

a metal layer provided on the film.

Claims 2-20 (Canceled).

Claim 21 (New): The probe device recited in Claim 1 wherein said wiring patterns comprise nickel.

Claim 22 (New): The probe device recited in Claim 21 wherein said wiring patterns are plated with gold.

Claim 23 (New): The probe device recited in Claim 1 wherein said contact pins comprise nickel.

Claim 24 (New): The probe device recited in Claim 23 wherein said contact pins are plated with gold.

Claim 25 (New): The probe device recited in Claim 1 wherein said metal layer comprises nickel.

Claim 26 (New): The probe device recited in Claim 1 wherein said metal layer comprises copper.

Claim 27 (New): The probe device recited in Claim 26 wherein said metal layer is plated with gold.

Claim 28 (New): The probe device recited in Claim 1 wherein said film comprises polyimide resin.

Claim 29 (New): The probe device recited in Claim 1 wherein a thermal expansion coefficient of said metal layer is the same as a thermal expansion coefficient of said contact pins.